

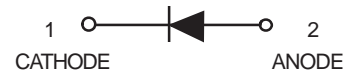
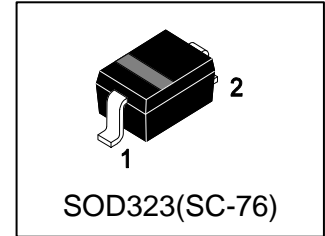
LRB501V-40T1G

S-LRB501V-40T1G

Surface Mount Schottky Diode

1. FEATURES

- We declare that the material of product compliance with RoHS requirements and Halogen Free.
- S- prefix for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Small surface mounting type.
- High reliability.
- Low current rectification



2. DEVICE MARKING AND ORDERING INFORMATION

Device	Marking	Shipping
LRB501V-40T1G	4	3000/Tape&Reel
LRB501V-40T3G	4	10000/Tape&Reel

3. MAXIMUM RATINGS(Ta = 25°C)

Parameter	Symbol	Limits	Unit
Peak reverse voltage	VRM	45	V
DC reverse voltage	VR	40	V
Mean rectifying current	IO	0.1	A
Peak forward surge current (Note 1)	IFSM	1	A
Junction temperature	Tj	125	°C
Storage temperature	Tstg	-40~+125	°C
Power Dissipation	PD	200	mW

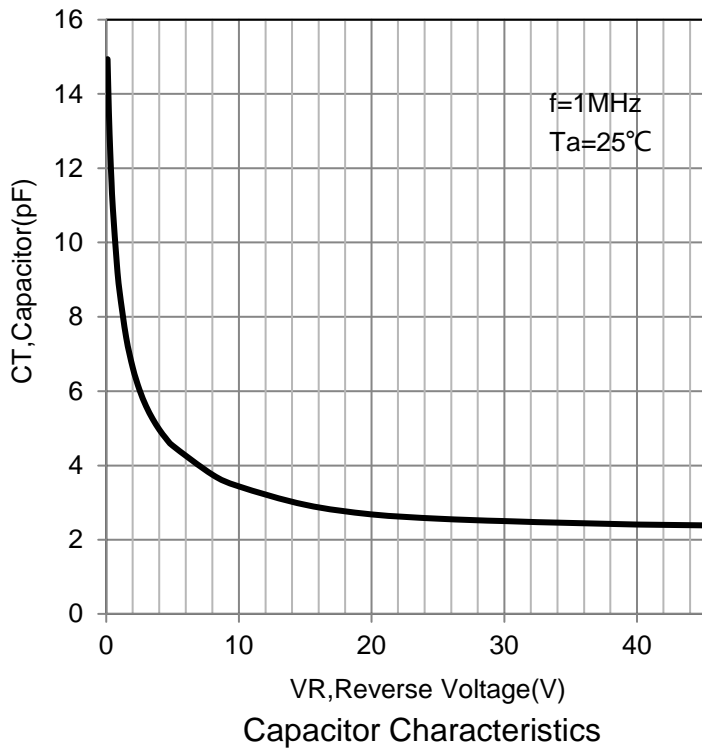
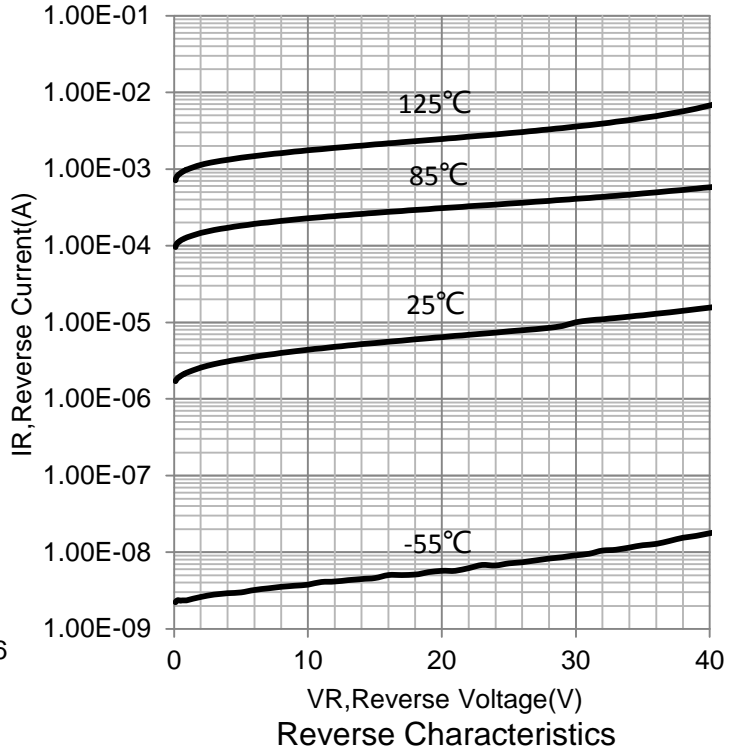
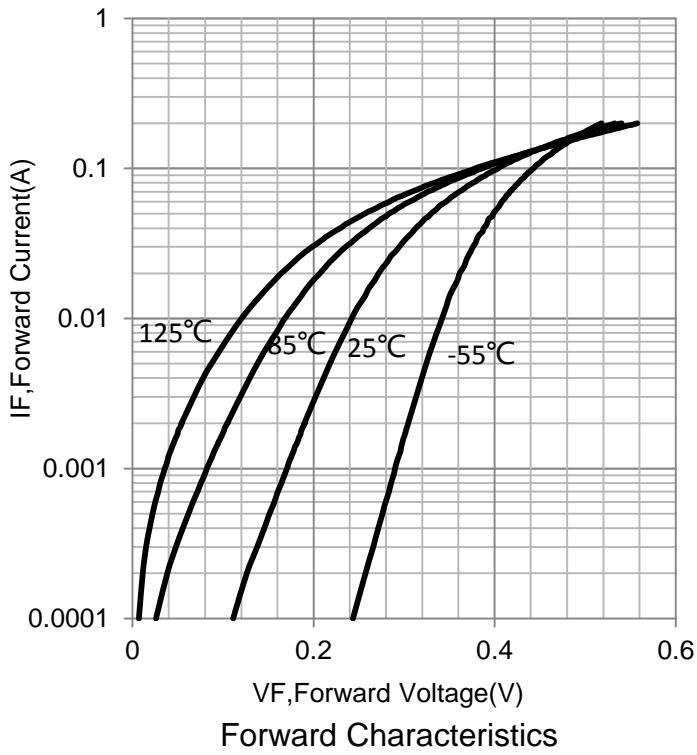
1.60 Hz for \varnothing

4. ELECTRICAL CHARACTERISTICS (Ta= 25°C)

Characteristic	Symbol	Min.	Typ.	Max.	Unit
Forward Voltage (IF =100mA)	VF	-	-	0.55	V
(IF = 10mA)		-	-	0.34	
Reverse current (VR =10V)	IR	-	-	30	μA
Capacitance between terminals (VR =10V, f=1MHz)	CT	-	3.5	-	pF

ESD sensitive product handling required.

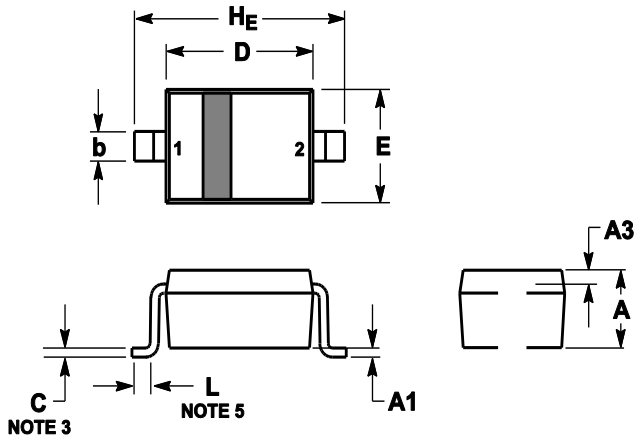
5.ELECTRICAL CHARACTERISTICS CURVES



6. OUTLINE AND DIMENSIONS

Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.8	0.9	1	0.031	0.035	0.04
A1	0	0.05	0.1	0	0.002	0.004
A3	0.15REF			0.006REF		
b	0.25	0.32	0.4	0.01	0.012	0.016
C	0.089	0.12	0.177	0.003	0.005	0.007
D	1.6	1.7	1.8	0.062	0.066	0.07
E	1.15	1.25	1.35	0.045	0.049	0.053
L	0.08			0.003		
H _E	2.3	2.5	2.7	0.09	0.098	0.105

7. SOLDERING FOOTPRINT

